

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.020mm	3.5	
3	L1_Top	Copper	0.072mm		
4	Dielectric1	FR-4	1.500mm	4.2	
5	L2_Bot	Copper	0.072mm		
6	Bottom Solder	Solder Resist	0.020mm	3.5	
7	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)
∇	4	43.31mil (1.100mm)	PTH	Round	L1_Top - L2_Bot	Pad	(Mixed)	(Mixed)			
□	658	11.81mil (0.300mm)	PTH	Round	L1_Top - L2_Bot	Via	Rounded	v60h30m0mx0			
	662 Total										

Infineon Technologies AG
IFAT DC ATP BP ASE
Am Campeon 1-12
85579 NEUBIBERG - GERMANY

ENGINEER:

PCB DESIGNER: V. Nita

TITLE: Power Shift Board 75x35

DATE: 8/5/2018

PART NO.:

REL: REL

REV: V1.1

SVN REVISION: 6608 [Locally Modified]

FILE NAME: Power_shift_board_70x35.PcbDoc

APRV: M. Schrodi

SCALE: 1:1

© © Infineon Technologies AG 2017. All Rights Reserved.